CHO-BOND® 584-208 TWO COMPONENT ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE SYSTEM



Customer Value Proposition:

CHO-BOND 584-208 is a two-component, silver filled conductive epoxy adhesive system designed for applications where a strong, highly conductive electrical bond must be achieved. CHO-BOND 584-208 is recommended for applications which require a conductive epoxy with an extended working life such as high volume part dispensing or complex part assembly operations.

Curing of CHO-BOND 584-208 can be achieved in as little as 45 minutes with heat to minimize equipment downtime and increase manufacturing throughput. With a 1:1 weight mix ratio, CHO-BOND 584-208 is easy to handle and use. Typical applications include bonding and grounding of electrical components, cold soldering, and bonding and sealing machined enclosures.

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Features and Benefits:

- Two component
- Silver filler

Medium paste

No VOCs

- Epoxy
- Fast heat cure, increases throughput, minimizes equipment downtime.
 - Good conductivity 0.002 ohm-cm
 - 60 minute working life, works well over wide temperature range, good chemical resistance >1000 psi lap shear, good for permanently bonding surfaces.
- 1:1 Weight mix ratio Easy to weigh out and mix.
 - May be dispensed out of very small needles, fill small cracks and voids. Can be used on overhead or vertical surfaces
 - Minimal shrinkage, no permits or ventilation required

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CHO-BOND 584-208 - Product Information

Table 1 Typical Properties

| Typical Properties | Typical Values | Test Method | |
|---|---|-----------------|-------|
| Polymer | Ероху | N/A | |
| Filler | Silver | N/A | |
| Mix Ratio, A : B (by weight) | 1:1 | N/A | |
| Color | Silver | N/A | (Q) |
| Consistency | Medium Paste | N/A | (Q) |
| Maximum DC Volume Resistivity (Cure Cycle 1) | 0.002 ohm-cm | CHO-95-40-5101* | (Q/C) |
| Minimum Lap Shear Strength (Cure Cycle 1) | 1000 psi (6895 kPa) | CHO-95-40-5300* | (Q/C) |
| Specific Gravity (Room Temp Cure) | 2.6 | ASTM D792 | (Q/C) |
| Hardness (Cure Cycle 1) | 80 Shore D | ASTM-D2240 | (Q) |
| Continuous Use Temperature | - 62°C to 100°C (-80°F to 212°F) | N/A | (Q) |
| Elevated Temperature Cure Cycle | Cure Cycle Option 1: 0.75 hour @ 100°C (212°F) Cure Cycle Option 2: 2.0 hours @ 65°C (150°F) | N/A | |
| Room Temperature Cure | 24 hours | N/A | (Q) |
| Working Life | 1.0 hours | N/A | |
| Shelf Life, unopened | 9 months @ 25°C (77°F) | N/A (Q) | |
| Minimum thickness recommended | 0.001 in (0.03 mm) | N/A | |
| Maximum thickness recommended | None | N/A | |
| Volatile Organic Content (VOC) | 0 g/l | Calculated | |
| Typical Coverage Area at 0.001" Thick per Pound (454 grams) | 10,500 in ² (67,742 cm ²) | N/A | |

Note: N/A - Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

This test Method is available from Parker Chomerics.

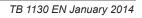
Table 2 Ordering Information

| Product | Weight (grams) | Packaging | Part Number | Primer Included |
|------------------|----------------|---|-----------------|-----------------|
| CHO-BOND 584-208 | 85 | 2 component, 4 fluid ounce polypropylene kit | 50-00-0584-0208 | Not required |
| | 454 | 2 component, 16 fluid ounce polypropylene kit | 50-01-0584-0208 | Not required |

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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